

(NOTE:For new designs, we recommend IR's new product IRS2153D)

IR2153(D)(S)&(PbF)

SELF-OSCILLATING HALF-BRIDGE DRIVER

Features

- Integrated 600V half-bridge gate driver
- 15.6V zener clamp on Vcc
- True micropower start up
- Tighter initial deadtime control
- Low temperature coefficient deadtime
- Shutdown feature (1/6th Vcc) on C_T pin
- Increased undervoltage lockout Hysteresis (1V)
- Lower power level-shifting circuit
- Constant LO, HO pulse widths at startup
- Lower di/dt gate driver for better noise immunity
- Low side output in phase with RT
- Internal 50nsec (typ.) bootstrap diode (IR2153D)
- Excellent latch immunity on all inputs and outputs
- ESD protection on all leads
- Also available LEAD-FREE

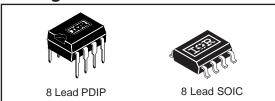
Description

The IR2153D(S) are an improved version of the popular IR2155 and IR2151 gate driver ICs, and incor-

Product Summary

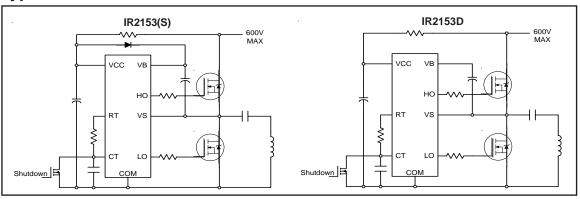
Voffset	600V max.
Duty Cycle	50%
T _r /T _p	80/40ns
V _{clamp}	15.6V
Deadtime (typ.)	1.2 µs

Packages



porates a high voltage half-bridge gate driver with a front end oscillator similar to the industry standard CMOS 555 timer. The IR2153 provides more functionality and is easier to use than previous ICs. A shutdown feature has been designed into the C_T pin, so that both gate driver outputs can be disabled using a low voltage control signal. In addition, the gate driver output pulse widths are the same once the rising undervoltage lockout threshold on V_{CC} has been reached, resulting in a more stable profile of frequency vs time at startup. Noise immunity has been improved significantly, both by lowering the peak di/dt of the gate drivers, and by increasing the undervoltage lockout hysteresis to 1V. Finally, special attention has been payed to maximizing the latch immunity of the device, and providing comprehensive ESD protection on all pins.

Typical Connections



Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units	
V _B	High side floating supply voltage		-0.3	625	
VS	High side floating supply offset voltage		V _B - 25	V _B + 0.3	
V _{HO}	High side floating output voltage		V _S - 0.3	V _B + 0.3	
V _{LO}	Low side output voltage		-0.3	V _{CC} + 0.3	· V
V _{RT}	R _T pin voltage		-0.3	V _{CC} + 0.3	
V _{CT}	C _T pin voltage	-0.3	V _{CC} + 0.3		
Icc	Supply current (note 1)		_	25	mA
I _{RT}	R _T pin current	-5	5		
dV _S /dt	Allowable offset voltage slew rate		-50	50	V/ns
PD	Maximum power dissipation @ T _A ≤ +25°C	(8 Lead DIP)	_	1.0	w
		(8 Lead SOIC)	_	0.625	, vv
Rth _{JA}	Thermal resistance, junction to ambient	Thermal resistance, junction to ambient (8 Lead DIP)		125	°C/W
	(8 Lead SOIC)		_	200	- 'C/VV
TJ	Junction temperature	-55	150		
T _S	Storage temperature	-55	150	°C	
TL	Lead temperature (soldering, 10 seconds)		_	300	

Recommended Operating Conditions

For proper operation the device should be used within the recommended conditions.

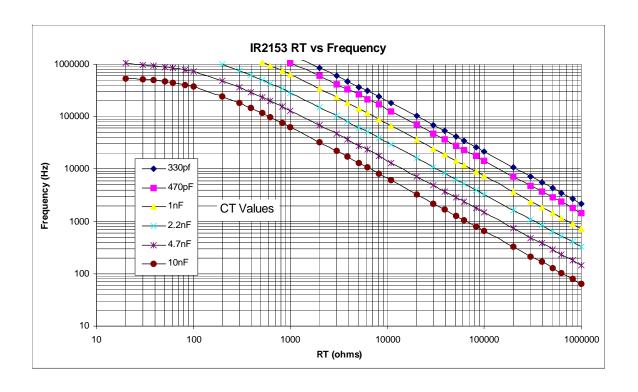
Symbol	Definition	Min.	Max.	Units
V _{BS}	High side floating supply voltage	V _{CC} - 0.7	VCLAMP	
Vs	Steady state high side floating supply offset voltage	-3.0 (note 2)	600	V
Vcc	Supply voltage	10	VCLAMP	
lcc	Supply current	(note 3)	5	mA
TJ	Junction temperature	-40	125	°C

- Note 1: This IC contains a zener clamp structure between the chip V_{CC} and COM which has a nominal breakdown voltage of 15.6V. Please note that this supply pin should not be driven by a DC, low impedance power source greater than the V_{CLAMP} specified in the Electrical Characteristics section.
- Note 2: Care should be taken to avoid output switching conditions where the V_S node flies inductively below ground by more than 5V
- Note 3: Enough current should be supplied to the V_{CC} pin of the IC to keep the internal 15.6V zener diode clamping the voltage at this pin.



Recommended Component Values

Symbol	Component	Min.	Max.	Units
R _T	Timing resistor value	10	_	kΩ
C _T	C _T pin capacitor value	330	_	pF



Electrical Characteristics

 V_{BIAS} (V_{CC} , V_{BS}) = 12V, C_L = 1000 pF, C_T = 1 nF and T_A = 25°C unless otherwise specified. The V_{IN} , V_{TH} and I_{IN} parameters are referenced to COM. The V_O and I_O parameters are referenced to COM and are applicable to the respective output leads: HO or LO.

Low Voltage Supply Characteristics							
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions	
V _{CCUV+}	Rising V _{CC} undervoltage lockout threshold	8.1	9.0	9.9			
V _{CCUV} -	Falling V _{CC} undervoltage lockout threshold	7.2	8.0	8.8	V		
VCCUVH	V _{CC} undervoltage lockout Hysteresis	0.5	1.0	1.5	1		
IQCCUV	Micropower startup V _{CC} supply current	_	75	150	μА	V _{CC} ≤V _{CCUV} -	
IQCC	Quiescent V _{CC} supply current	_	500	950	μΛ		
VCLAMP	V _{CC} zener clamp voltage	14.4	15.6	16.8	V	I _{CC} = 5mA	

Floating Supply Characteristics

Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
I _{QBSUV}	Micropower startup V _{BS} supply current	_	0	10	μА	Vcc≤Vccuv-
I _{QBS}	Quiescent VBS supply current	_	30	50	μΑ	
V _{BSMIN}	Minimum required V _{BS} voltage for proper	_	4.0	5.0	V	$V_{CC}=V_{CCUV+} + 0.1V$
	functionality from R _T to HO					
I _{LK}	Offset supply leakage current	_	_	50	μΑ	$V_{B} = V_{S} = 600V$
VF	Bootstrap diode forward voltage (IR2153D)	0.5	_	1.0	V	IF = 250mA

Oscillator I/O Characteristics

Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
fosc	Oscillator frequency	19.4	20	20.6	1-11-	$R_T = 36.9k\Omega$
		94	100	106	kHz	$RT = 7.43k\Omega$
d	RT pin duty cycle	48	50	52	%	fo < 100kHz
I _{CT}	C _T pin current	_	0.001	1.0	uA	
I _{CTUV}	UV-mode C _T pin pulldown current	0.30	0.70	1.2	mA	V _{CC} = 7V
VCT+	Upper C _T ramp voltage threshold	_	8.0	_		
Vст-	Lower C _T ramp voltage threshold	_	4.0	_	V	
VCTSD	CT voltage shutdown threshold	1.8	2.1	2.4	Ī	
V _{RT+}	High-level RT output voltage, VCC - VRT	_	10	50		I _{RT} = 100μA
		_	100	300		I _{RT} = 1mA
VRT-	Low-level R _T output voltage	_	10	50	1	I _{RT} = 100μA
		_	100	300	\/	$I_{RT} = 1mA$
VRTUV	UV-mode R _T output voltage	_	0	100	mV	V _{CC} ≤V _{CCUV} -
VRTSD	SD-Mode RT output voltage, VCC - VRT	_	10	50	1	$I_{RT} = 100 \mu A$,
						V _{CT} = 0V
		_	10	300	1	$I_{RT} = 1mA$,
						V _{CT} = 0V

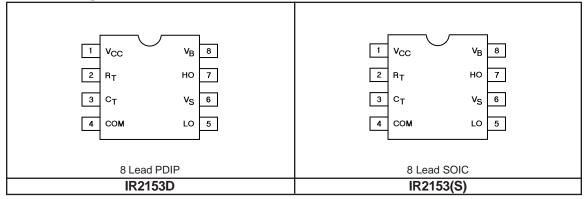
Electrical Characteristics (cont.)

Gate D	Gate Driver Output Characteristics							
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions		
VoH	High level output voltage, V _{BIAS} -V _O		0	100		I _O = OA		
VOL	Low-level output voltage, VO	_	0	100	mV	I _O = OA		
VOL_UV	UV-mode output voltage, VO	_	0	100	1111	I _O = OA		
						$I_O = OA$ $V_{CC} \le V_{CCUV}$		
tr	Output rise time	_	80	150				
tf	Output fall time	_	45	100	nsec			
t _{sd}	Shutdown propogation delay	_	660	_	1			
td	Output deadtime (HO or LO)	0.75	1.20	1.65	μsec			

Lead Definitions

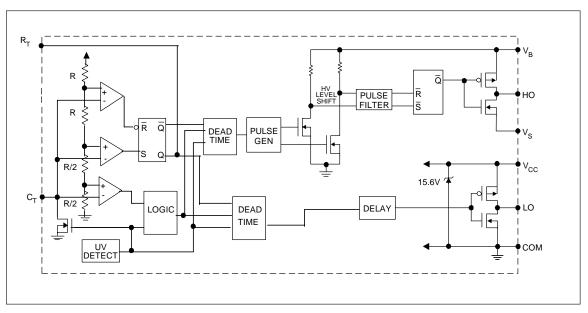
Symbol	Description
Vcc	Logic and internal gate drive supply voltage
R _T	Oscillator timing resistor input
C _T	Oscillator timing capacitor input
COM	IC power and signal ground
LO	Low side gate driver output
VS	High voltage floating supply return
НО	High side gate driver output
V _B	High side gate driver floating supply

Lead Assignments

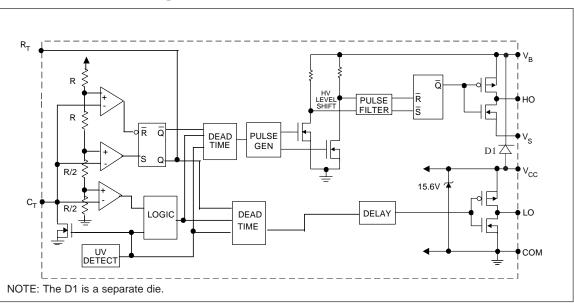


NOTE: The IR2153D is offered in 8 lead PDIP only.

Functional Block Diagram for IR2153(S)

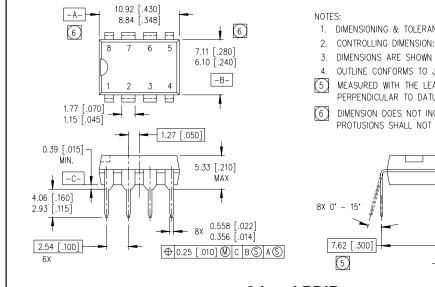


Functional Block Diagram for IR2153D

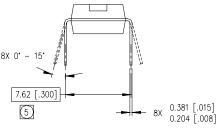


IR2153(D)(S) & (PbF)

NOTE: For new designs, we recommend IR's new product IRS2153D

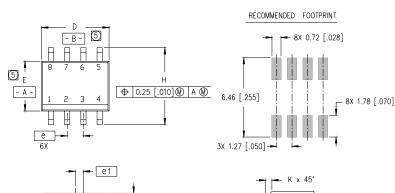


- 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- OUTLINE CONFORMS TO JEDEC OUTLINE MS-001AB.
- MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM PLANE C.
- DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS SHALL NOT EXCEED 0.25 [.010].

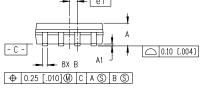


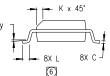
8 Lead PDIP

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DILL	INCHES		MILLIME	TERS
DIM	MIN	MAX	MIN	MAX
Α	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
В	.014	.018	0.36	0.46
С	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
Ε	.150	.157	3.81	3.99
е	.050 BASIC		1.27 B	ASIC
e 1	.025 B	ASIC	0.635	BASIC
Н	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	.016	.050	0.41	1.27
у	0.	8.	0.	8.





NOTES:

- 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [.006].
- DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

8 Lead SOIC

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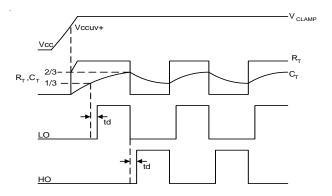


Figure 1. Input/Output Timing Diagram

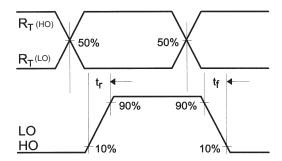


Figure 2. Switching Time Waveform Definitions

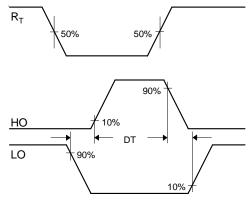
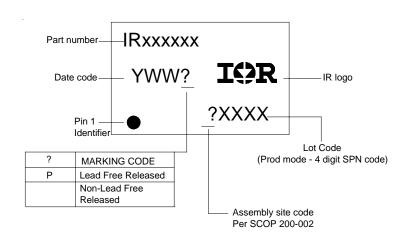


Figure 3. Deadtime Waveform Definitions

LEADFREE PART MARKING INFORMATION



ORDER INFORMATION

Basic Part (Non-Lead Free)

8-Lead PDIP IR2153 order IR2153 8-Lead SOIC IR2153S order IR2153S 8-Lead PDIP IR2153D order IR2153D

Leadfree Part

8-Lead PDIP IR2153 order IR2153PbF 8-Lead SOIC IR2153S order IR2153SPbF 8-Lead PDIP IR2153D order IR2153DPbF



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This product has been qualified per industrial level

Data and specifications subject to change without notice. 2/8/2006